Preferred Device

POWERTAP[™] II SWITCHMODE[™] Power Rectifier

This state-of-the-art device uses the Schottky Barrier principle with a platinum barrier metal.

Features

- Dual Diode Construction; May Be Paralleled for Higher Current Output
- Guardring for Stress Protection
- Low Forward Voltage
- 150°C Operating Junction Temperature
- Guaranteed Reverse Avalanche
- Pb-Free Package is Available*

Mechanical Characteristics

- Case: Epoxy, Molded with Metal Heatsink Base
- Weight: 80 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant
- Top Terminal Torque: 25-40 lb-in Max
- Base Plate Torques: See Procedure Given in the Package Outline Section

MAXIMUM RATINGS

Peak Repetitive Reverse Voltage V V Working Peak Reverse Voltage V V DC Blocking Voltage V V Average Rectified Forward Current JF(AV) V				
Working Peak Reverse Voltage VRWM DC Blocking Voltage VR Average Rectified Forward Current IF(AV)	Rating	Symbol	Value	Unit
Average Rectified Forward Current	Vorking Peak Reverse Voltage	V _{RWM}	45	V
(Hated $V_{\rm R}$, $\Gamma_{\rm C} = 140$ C) Per Leg 100 Per Device 200	Rated V _R , T _C = 140°C) Per L	.eg	100 200	A
Peak Repetitive Forward Current, (Rated V _R , Square Wave, 20 kHz, T _C = 140°C)IFRMIFRM20 kHz, T _C = 140°C)Per Leg200	Rated V _R , Square Wave,		200	A
Non-Repetitive Peak Surge Current IFSM 1500 (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) 1500	Surge Applied at Rated Load Conditio	IFSM	1500	A
Peak Repetitive Reverse Current I _{RRM} A (2.0 μs, 1.0 kHz) Per Leg 2.0 4			2.0	A
Storage Temperature Range T _{stg} -55 to +150 °	otorage Temperature Range	T _{stg}	–55 to +150	°C
Operating Junction Temperature T_J -55 to +150 °	perating Junction Temperature	TJ	-55 to +150	°C
Voltage Rate of Change (Rated V _R) dv/dt 10,000 V/	oltage Rate of Change (Rated V _R)	dv/dt	10,000	V/μs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



ON Semiconductor®

http://onsemi.com

SCHOTTKY BARRIER RECTIFIER 200 AMPERES, 45 VOLTS

POWERTAP II CASE 357C PLASTIC

MARKING DIAGRAM



B20045T	= Specific Device Code
MCC	= Mold Compound Code
А	= Assembly Location
YY	= Year
WW	= York Week
G	= Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
MBRP20045CT	POWERTAP II	25 Units/Tray
MBRP20045CTG	POWERTAP II (Pb-Free)	25 Units/Tray

Preferred devices are recommended choices for future use and best overall value.

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THERMAL CHARACTERISTICS (Per Leg)

Rating	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.6	°C/W
ELECTRICAL CHARACTERISTICS (Per Leg)			
Instantaneous Forward Voltage (Note 1) ($i_F = 200 \text{ Amps}, T_J = 25^{\circ}\text{C}$) ($i_F = 200 \text{ Amps}, T_J = 125^{\circ}\text{C}$)	VF	0.89 0.78	V
Instantaneous Reverse Current (Note 1) (Rated dc Voltage, T _J = 125°C) (Rated dc Voltage, T _J = 25°C)	İR	50 0.5	mA

1. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq [2.0%.

MAXIMUM MECHANICAL RATINGS

Terminal Penetration:	0.235 max
Terminal Torque:	25–40 in-lb max
Mounting Torque — Outside Holes:	30–40 in-lb max
Mounting Torque — Center Hole:	8–10 in-lb max
Seating Plane Flatness	1 mil per in. (between mounting holes)

POWERTAP MECHANICAL DATA APPLIES OVER OPERATING TEMPERATURE

2 Vertical Pull 2 in. Lever Pull 250 lbs. max

50 lbs. max

adiead to them adiead to them any Use of thematic any Use of the a Note: While the POWERTAP is capable of sustaining these vertical and levered tensions, the intimate contact between POWERTAP and heat sink may be lost. This could lead to thermal runaway. The use of very flexible leads is recommended for the anode connections. Use of thermal grease is highly recommended.

> http://onsemi.com 2

MOUNTING PROCEDURE

The POWERTAP package requires special mounting considerations because of the long longitudinal axis of the copper heat sink. It is important to follow the proper tightening sequence to avoid warping the heat sink, which can reduce thermal contact between the POWERTAP and heat sink.

2-3 TURNS

2-3 TURNS

5–10 IN-LB

POWER

HEAT

POWER

HEAT

HEAT

2-3 TURNS

FINGER-TIGHT

FINGER-TIGHT

2-3 TURNS

2-3 TURNS

10 IN-LB

TAP

SINK

TAP

SINK

SINK

STEP 1:

Locate the POWERTAP on the heat sink and start mounting bolts into the threads by hand (2 or 3 turns).

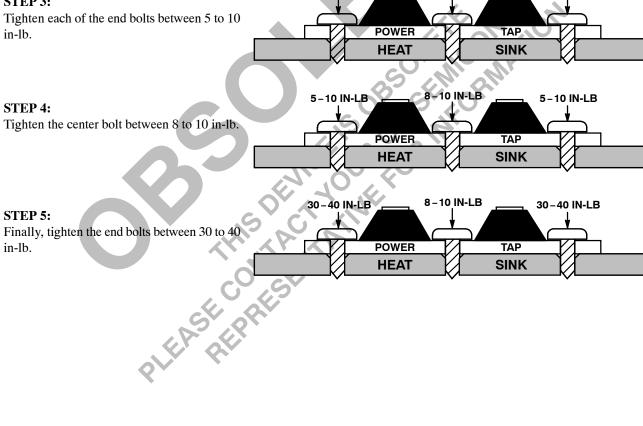
STEP 2:

Finger tighten the center bolt. The bolt may catch on the threads of the heat sink so it is important to make sure the face of the bolt or washer is in contact with the surface of the POWERTAP.

STEP 3:

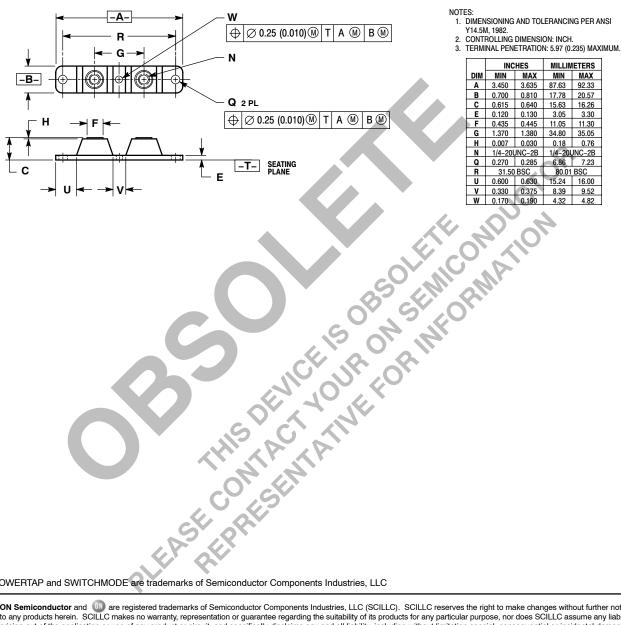
Tighten each of the end bolts between 5 to 10 in-lb.

STEP 4:



PACKAGE DIMENSIONS

CASE 357C-03 POWERTAP PLASTIC PACKAGE ISSUE E



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